

FUJI POWER MOSFET Super FAP-G Series

N-CHANNEL SILICON POWER MOSFET

Features

- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- Avalanche-proof

Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

Maximum ratings and characteristic Absolute maximum ratings

● (Tc=25°C unless otherwise specified)

Item	Symbol	Ratings	Unit
Drain-source voltage	V _{DS}	100	V
	V _{DSX} *5	70	V
Continuous drain current	I _D	±41	A
Pulsed drain current	I _{D(puls)}	±164	A
Gate-source voltage	V _{GS}	±30	V
Non-repetitive Avalanche current	I _{AS} *2	41	A
Maximum Avalanche Energy	E _{AS} *1	204.7	mJ
Maximum Drain-Source dV/dt	dV _{DS} /dt *4	20	kV/μs
Peak Diode Recovery dV/dt	dV/dt *3	5	kV/μs
Max. power dissipation	P _D	T _a =25°C	1.67
		T _c =25°C	150
Operating and storage temperature range	T _{ch}	+150	°C
	T _{stg}	-55 to +150	°C

*1 L=146μH, V_{CC}=48V, T_{ch}=25°C, See to Avalanche Energy Graph *2 T_{ch} ≤150°C

*3 I_F ≤ -I_D, -di/dt=50A/μs, V_{CC} ≤ BV_{DSS}, T_{ch} ≤ 150°C *4 V_{DS} ≤100V *5 V_{GS}=-30V

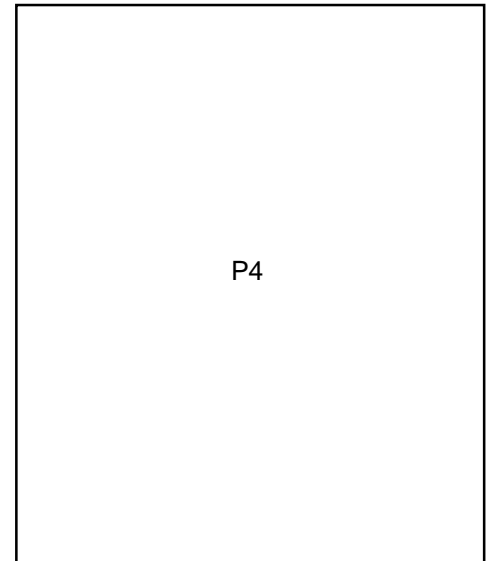
Electrical characteristics (T_c =25°C unless otherwise specified)

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 250μA V _{GS} =0V	100			V
Gate threshold voltage	V _{GS(th)}	I _D = 250μA V _{DS} =V _{GS}	3.0		5.0	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V V _{GS} =0V V _{DS} =80V V _{GS} =0V	T _{ch} =25°C		25	μA
			T _{ch} =125°C		250	
Gate-source leakage current	I _{GSS}	V _{GS} =±30V V _{DS} =0V		10	100	nA
Drain-source on-state resistance	R _{DS(on)}	I _D =15A V _{GS} =10V		34	44	mΩ
Forward transconductance	g _{fs}	I _D =15A V _{DS} =25V	9	18		S
Input capacitance	C _{iss}	V _{DS} =75V		1110	1665	pF
Output capacitance	C _{oss}	V _{GS} =0V		280	420	
Reverse transfer capacitance	C _{rss}	f=1MHz		22	33	
Turn-on time t _{on}	td(on)	V _{CC} =48V I _D =15A		16	24	ns
	t _r	V _{GS} =10V		23	35	
Turn-off time t _{off}	td(off)	R _{GS} =10 Ω		31	47	ns
	t _f			16	24	
Total Gate Charge	Q _G	V _{CC} =50V		32	48	nC
Gate-Source Charge	Q _{GS}	I _D =30A		13	20	
Gate-Drain Charge	Q _{GD}	V _{GS} =10V		9	14	
Avalanche capability	I _{AV}	L=146μH T _{ch} =25°C	41			A
Diode forward on-voltage	V _{SD}	I _F =30A V _{GS} =0V T _{ch} =25°C		1.10	1.65	V
Reverse recovery time	t _{rr}	I _F =30A V _{GS} =0V		0.1		μs
Reverse recovery charge	Q _{rr}	-di/dt=100A/μs T _{ch} =25°C		0.38		μC

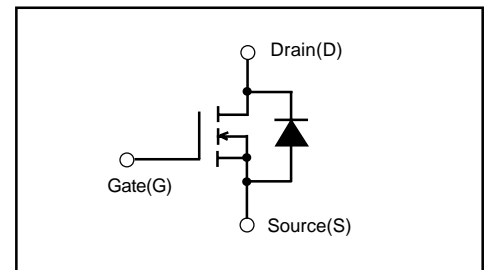
Thermal characteristics

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	R _{th(ch-c)}	channel to case			0.833	°C/W
	R _{th(ch-a)}	channel to ambient			75.0	°C/W

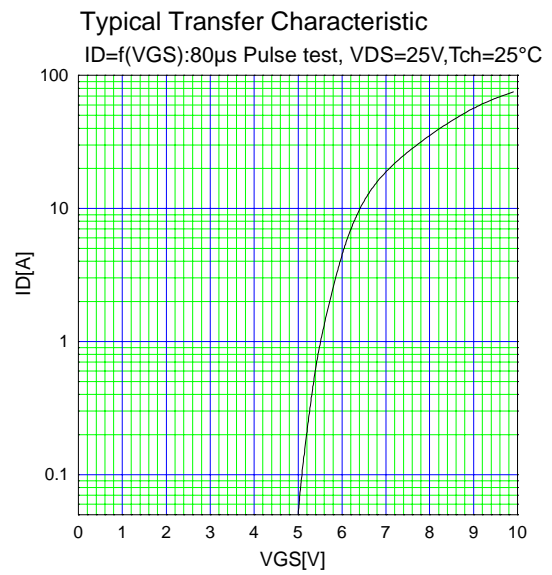
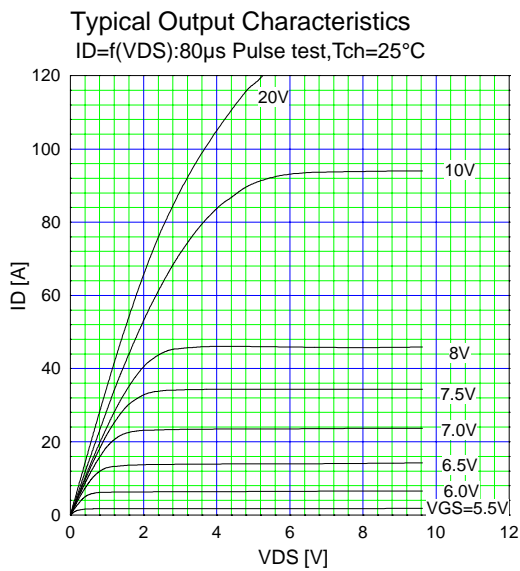
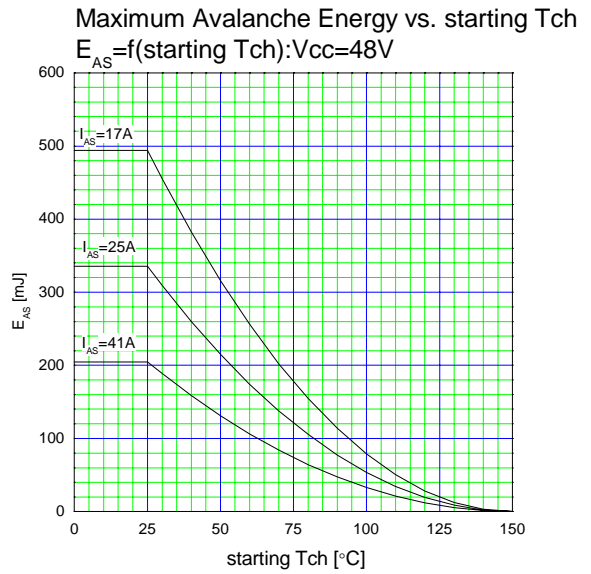
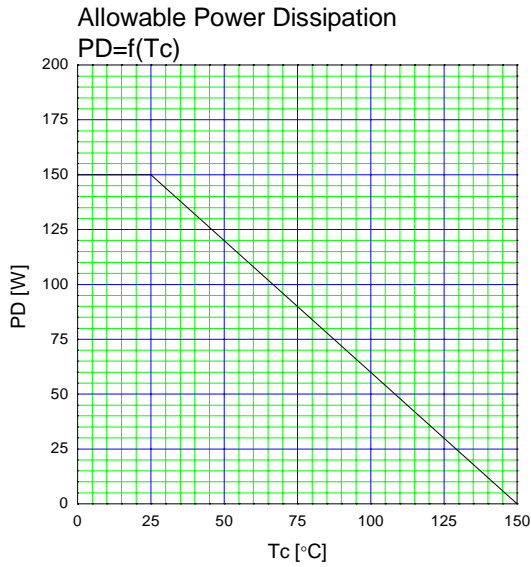
Outline Drawings (mm)



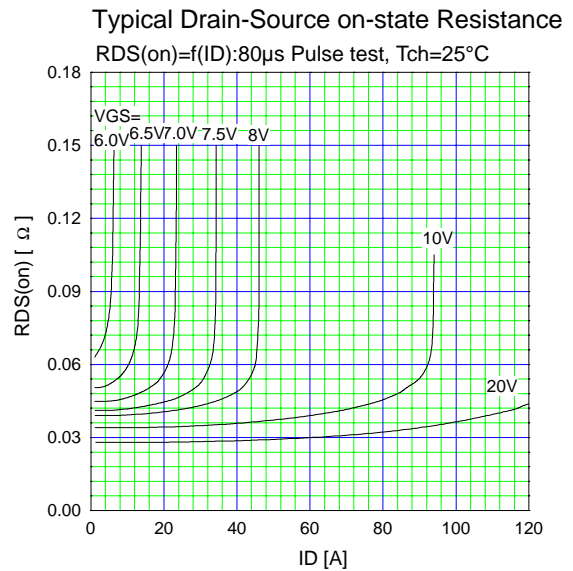
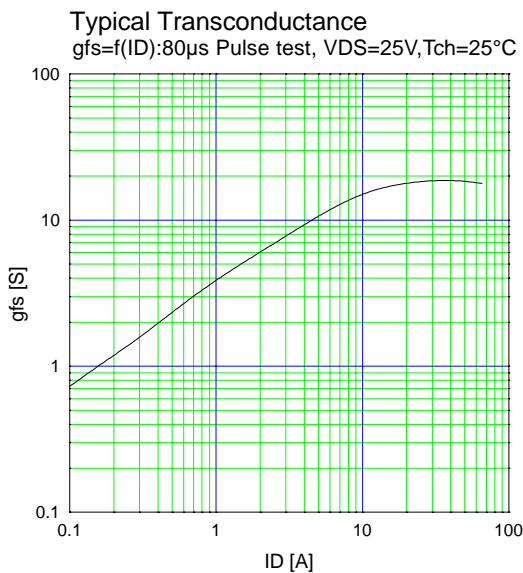
Equivalent circuit schematic

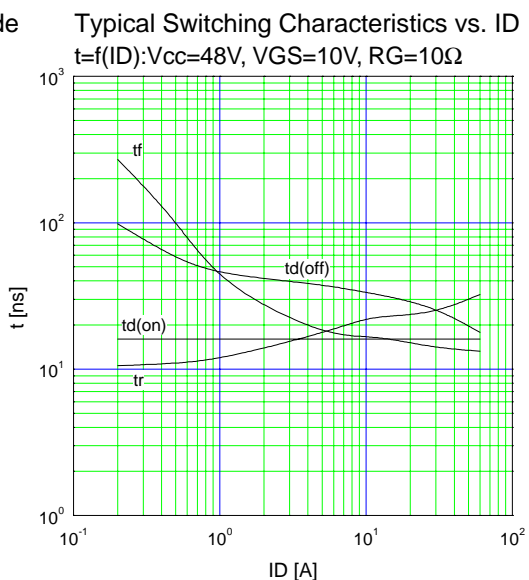
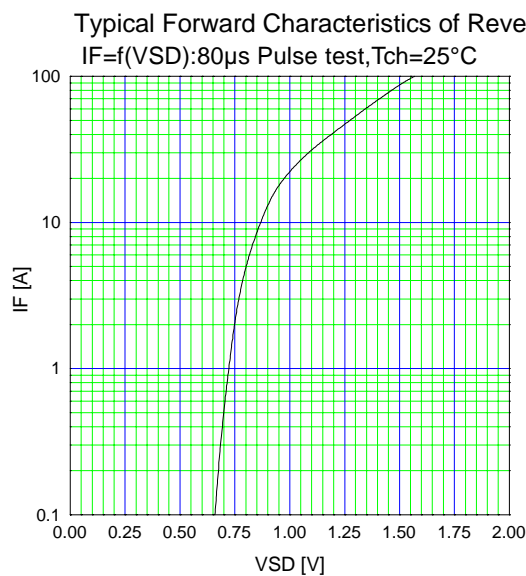
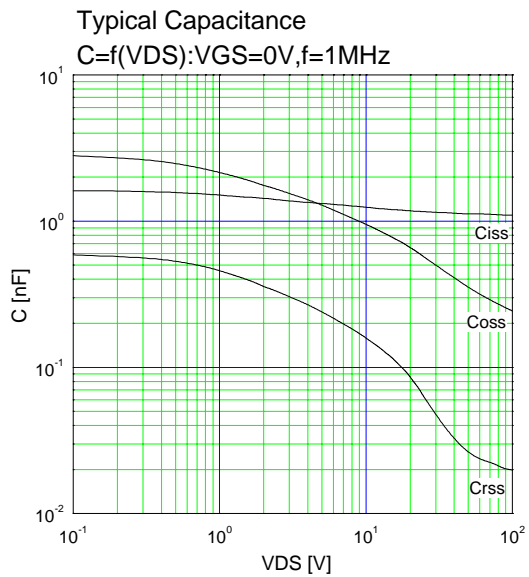
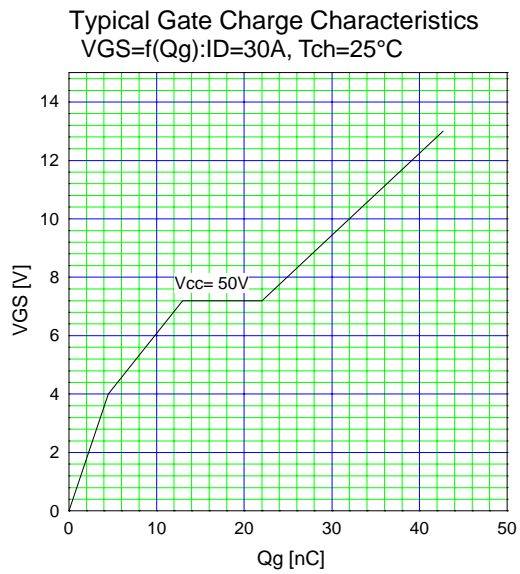
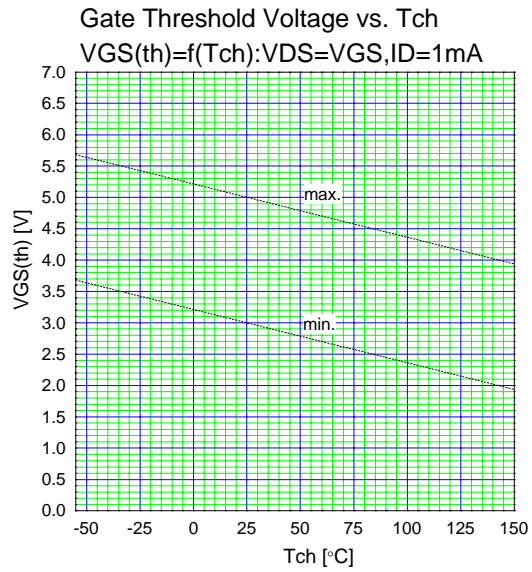
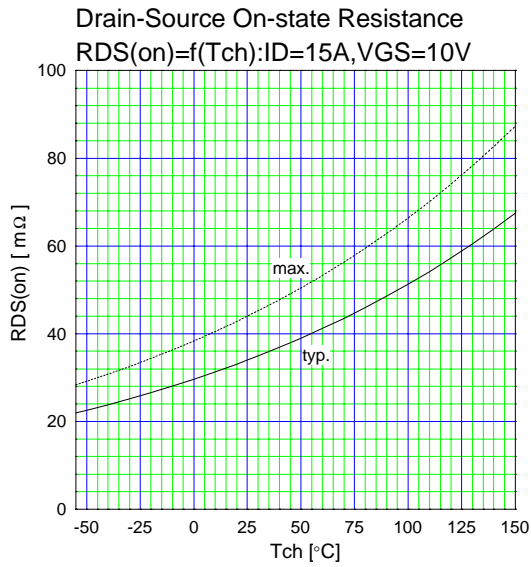


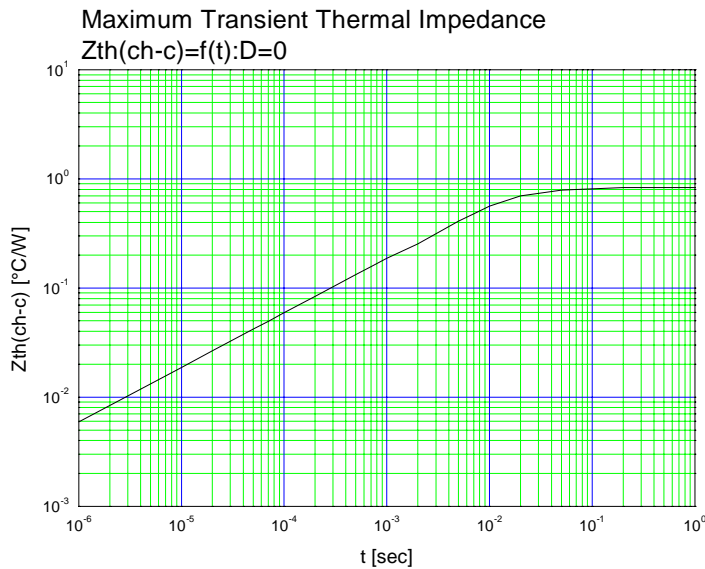
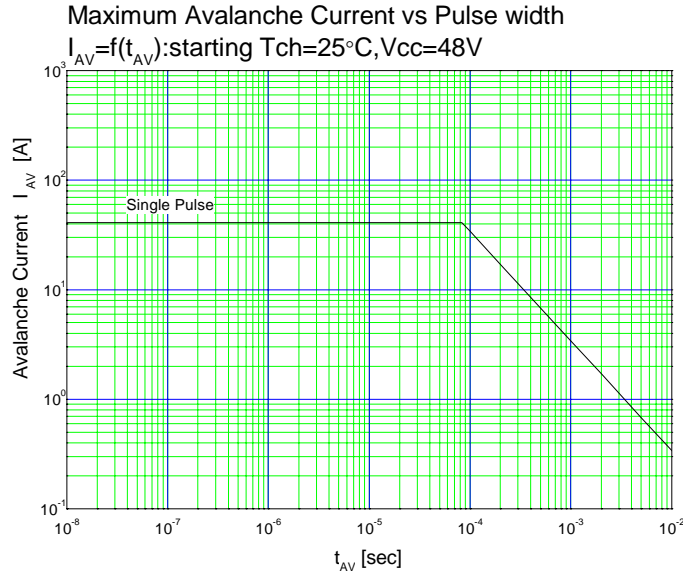
Characteristics



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Outline Drawings (mm)

